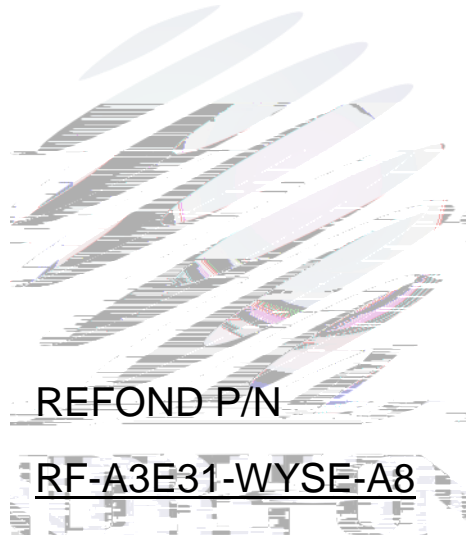


SPECIFICATION

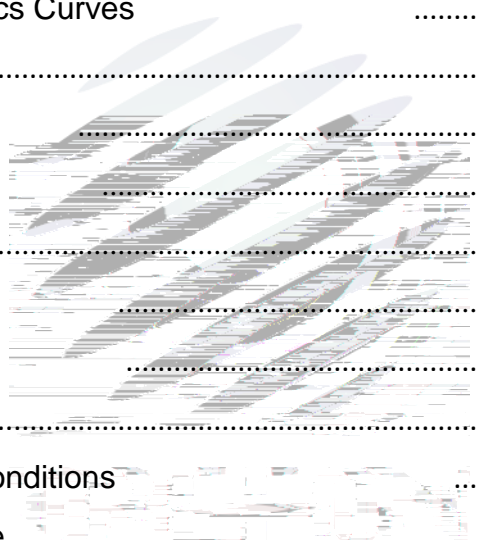


Mass Production



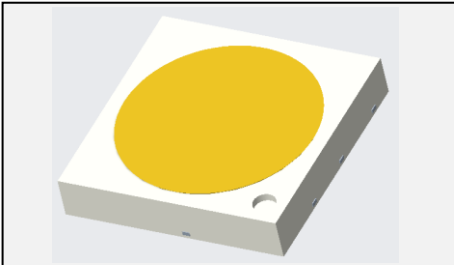
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1. Description

1.1



The White LED, which was fabricated by using a blue chip and the phosphor.

Product Package: 3.0mmX3.0mmX0.55mm.

LED

3.0mmX3.0mmX0.55mm

1.2 Features

- ▶ EMC Package. EMC
- ▶ Extremely wide viewing angle.
- ▶ Suitable for all SMT assembly and solder process. SMT
- ▶ Available on tape and reel.
- ▶ Moisture sensitivity level: Level 2. Level2
- ▶ Compliance with RoHS and REACH. RoHS REACH
- ▶ Qualifications: The product qualification test plan is based on the guidelines of AEC-Q102 Stress Test Qualification for Automotive Grade Discrete Semiconductors AEC-Q102

1.3 Application

- ▶ Automotive Lighting Interior and Exterior.

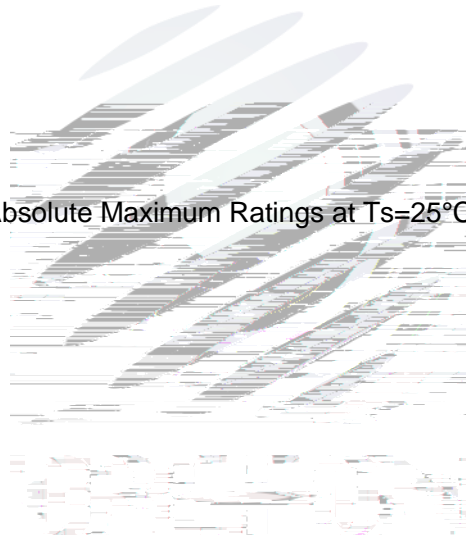




1.5 Product Parameters

 Table 1-1 Electrical / Optical Characteristics at $T_s=25^{\circ}\text{C}$

Item	Symbol	Test Condition	Value			Unit
			Min.	Typ.	Max.	
Forward Voltage	V_F	$I_F=150\text{mA}$	2.8	3.1	3.4	V
Reverse Current	I_R	$V_R=5\text{V}$	Not designed for reverse operation			
Luminous Flux	Φ	$I_F=150\text{mA}$	40.9	49	61.2	lm
Viewing Angle	2 θ 1/2	$I_F=$				

 Table 1-2 Absolute Maximum Ratings at $T_s=25^{\circ}\text{C}$


Notes

1. 1/10 Duty cycle, 10ms pulse width. 10ms, 1/10.
2. The above forward voltage measurement allowance tolerance is $\pm 0.1V$.
3. The above color coordinates measurement allowance tolerance is ± 0.005 . ± 0.005 .
4. The above luminous intensity measurement allowance tolerance $\pm 10\%$.
5. Care is to be taken that power dissipation does not exceed the absolute maximum rating of the product.
6. All measurements were made under the standardized environment of Refond.
7. When the LEDs are in operation the maximum current should be decided after measuring the package temperature, junction temperature should not exceed the maximum rate. LED
8. ESD yield is over 90% at 8000V ESD (HBM). ESD protection during products handling is needed. 90% LED ESD8000V

1.6 Bin Range Of Forward Voltage and Luminous Flux (IF=150mA)

BIN (IF=150mA)

Table 1-3

V _F V	G1	G2	H1	H2	I1	I2		
	2.8-2.9	2.9-3.0	3.0-3.1	3.1-3.2	3.2-3.3	3.3-3.4		
φ lm	NB	OA	OB	PA				
	40.9-45.3	45.3-50	50-55.3	55.3-61.2				



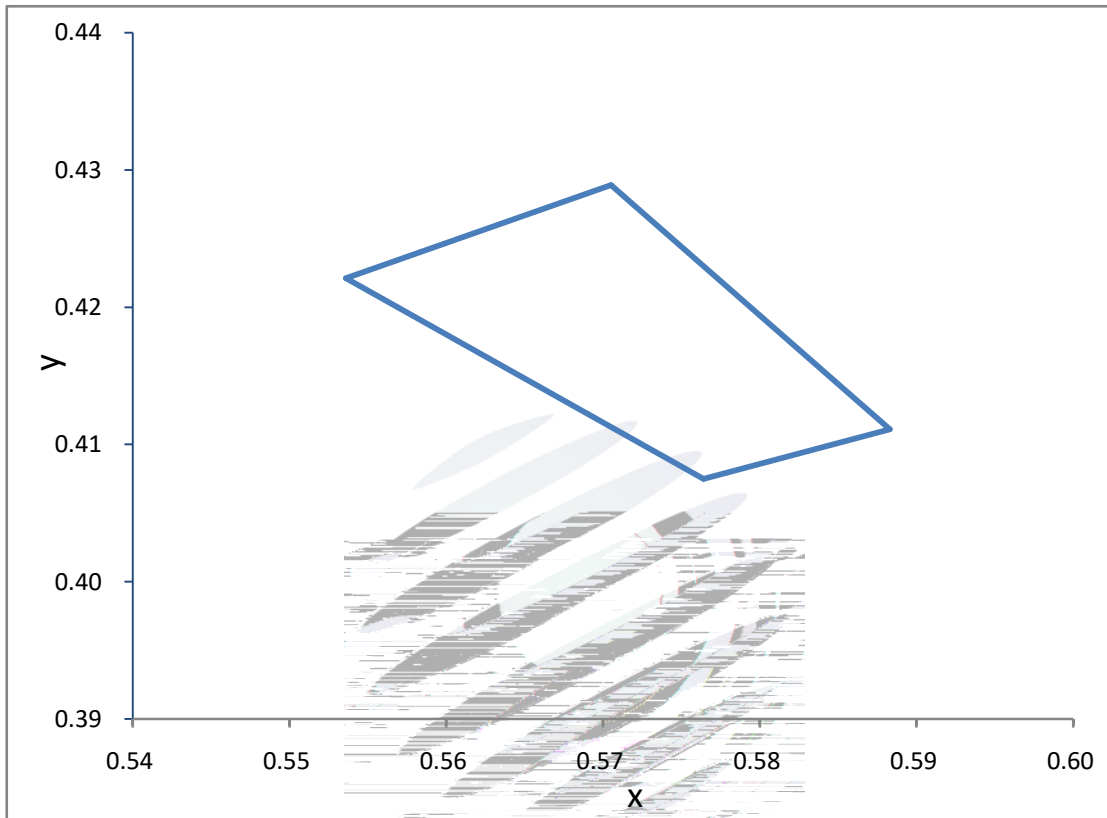


Fig. 1-6 The C.I.E Chromaticity Diagram CIE

Table 1-4

BIN CODE	CIE-X1	CIE-Y1	CIE-X2	CIE-Y2	CIE-X3	CIE-Y3	CIE-X4	CIE-Y4
5E	0.5536	0.4221	0.5764	0.4075	0.5883	0.4111	0.5705	0.4289



1.7 Typical Optical Characteristics Curves

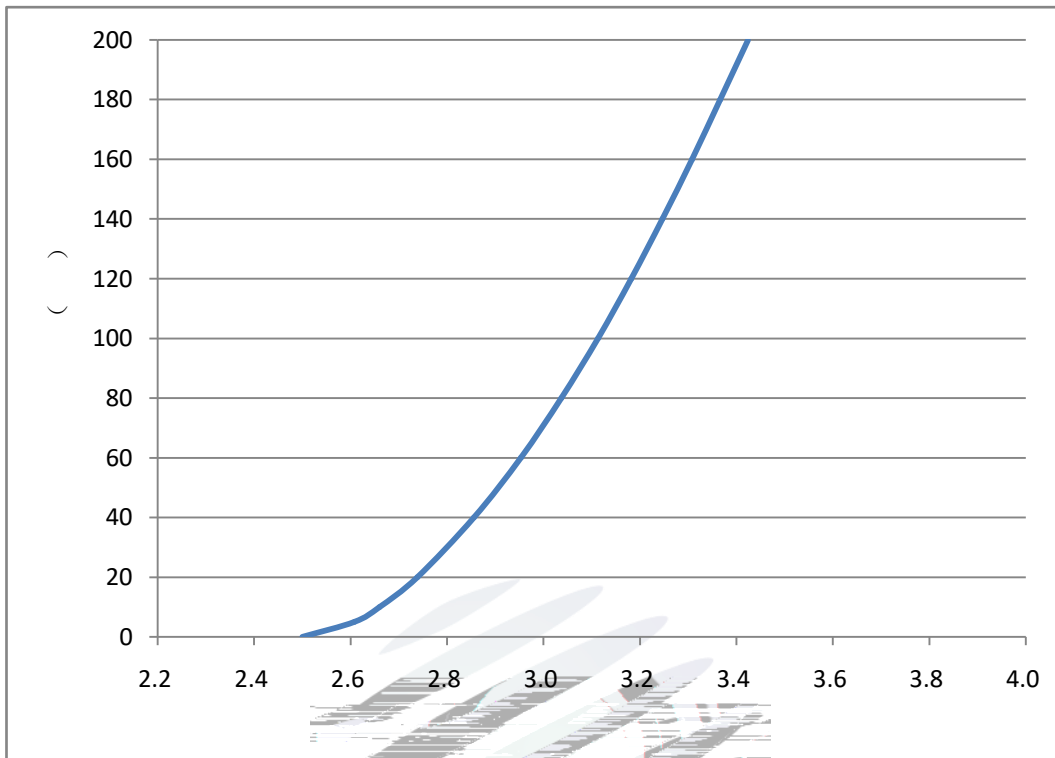


Fig. 1-7 Forward Voltage Vs Forward Current

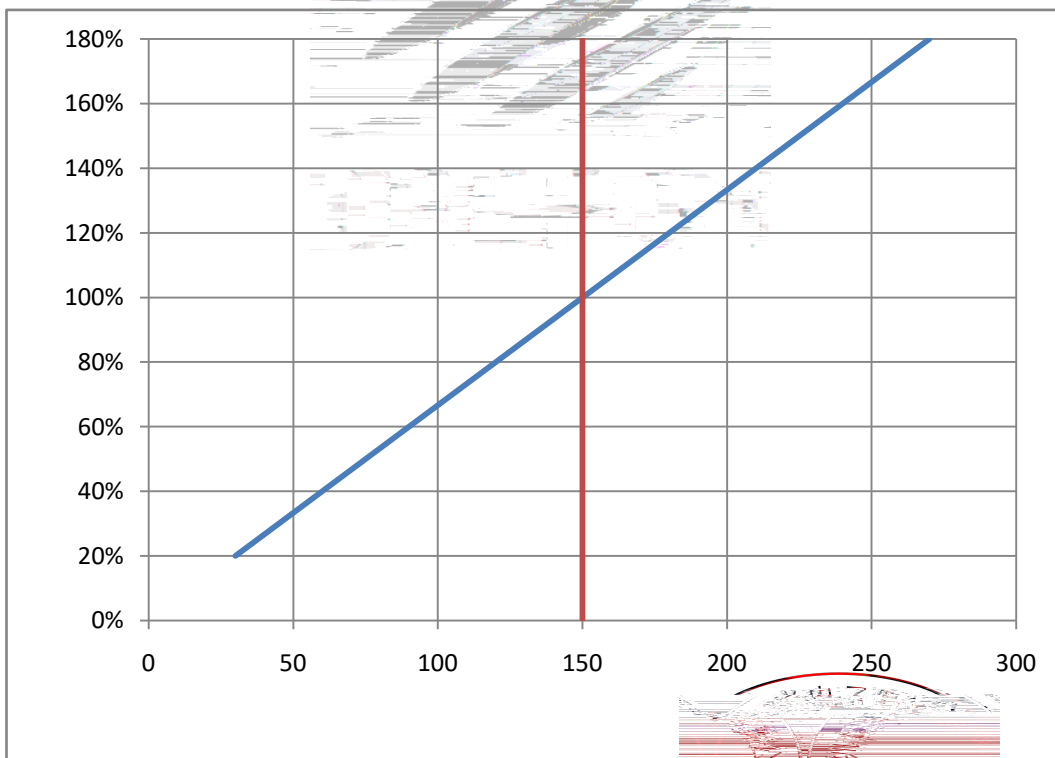


Fig. 1-8 Forward Current Vs Relative Intensity

Fig. 1-9 Solder Temperature Vs Relative Intensity

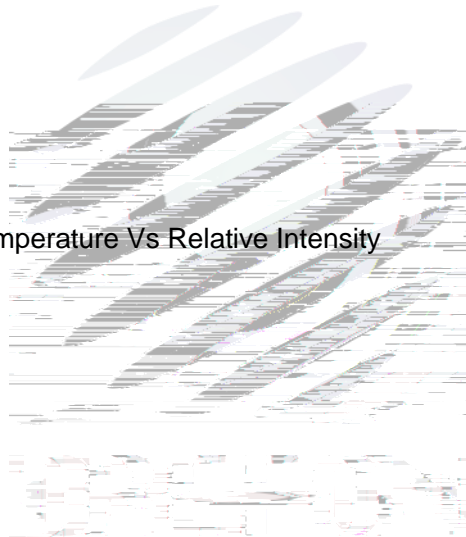


Fig. 1-10 Solder Temperature Vs

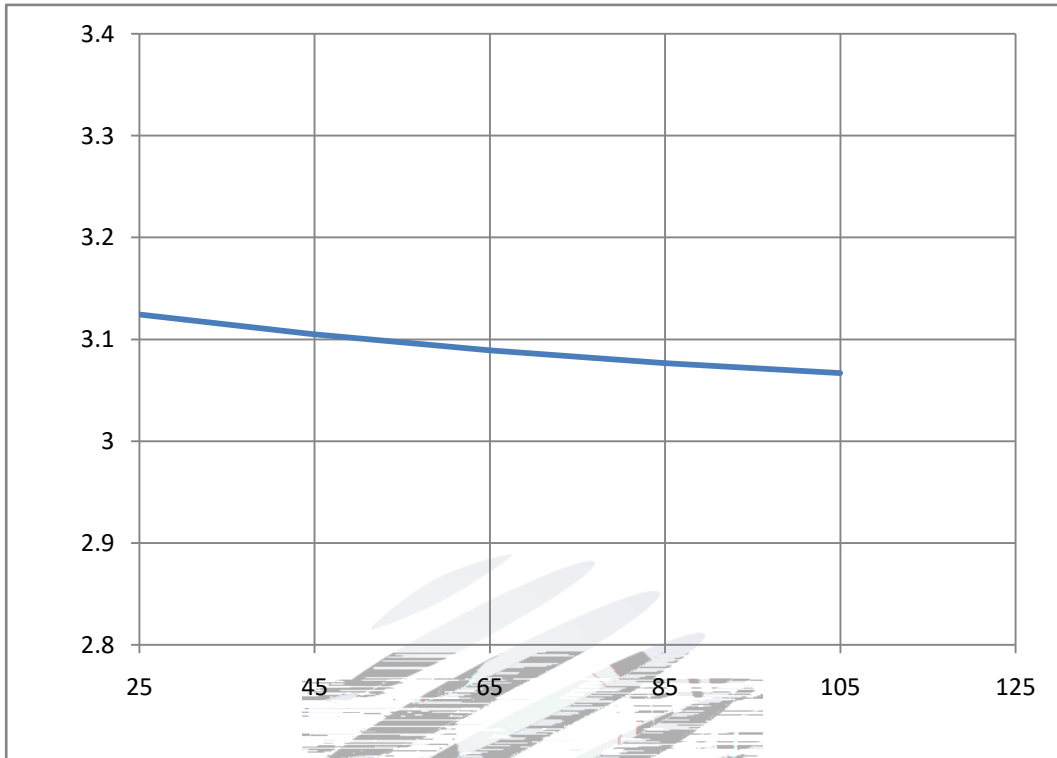


Fig. 1-11 Forward Voltage Vs Solder Temperature

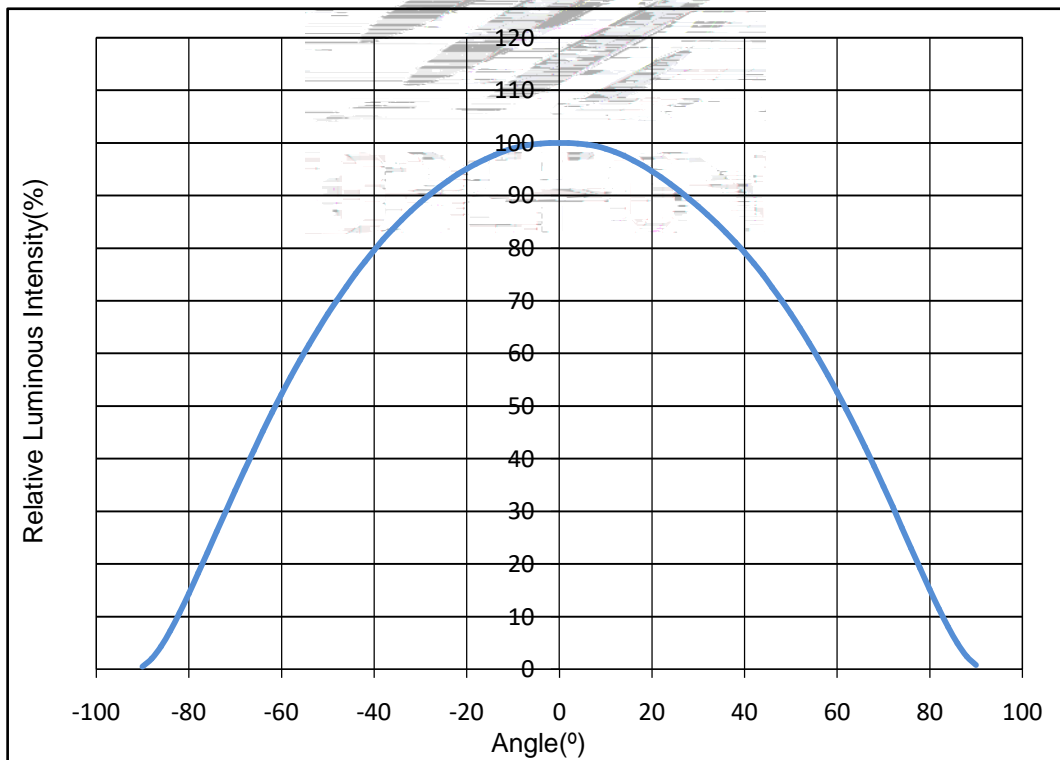


Fig. 1-12 Radiation diagram

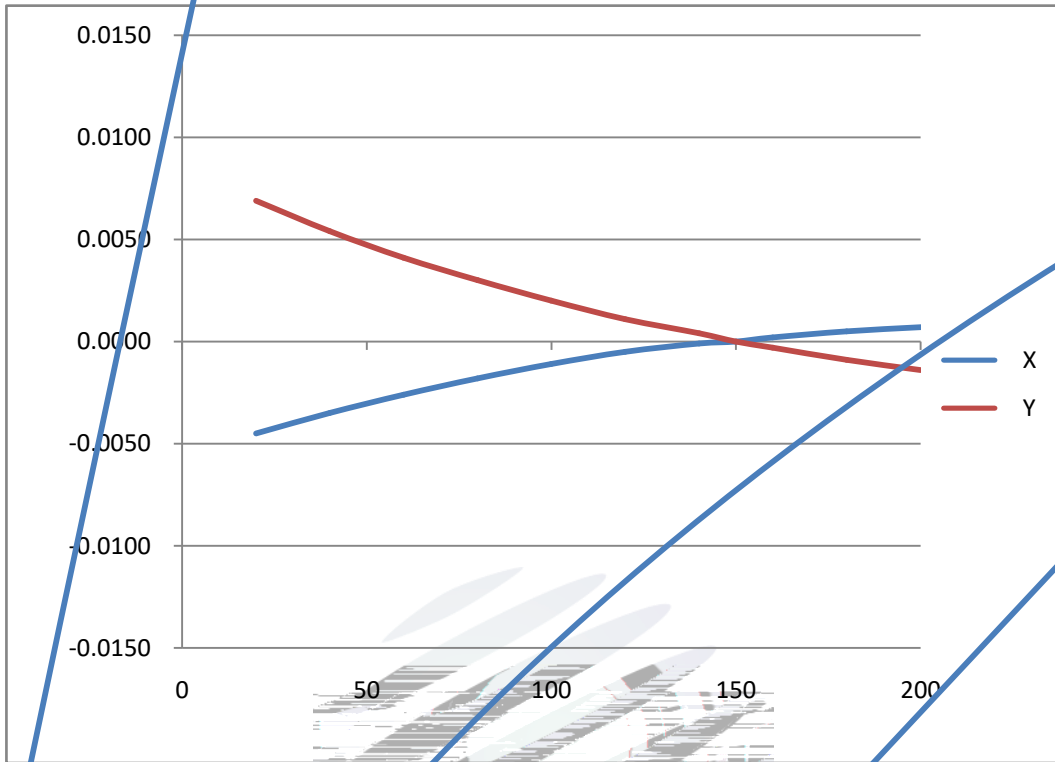


Fig. 1-13 Chromaticity Coordinate Shift Vs Forward Current

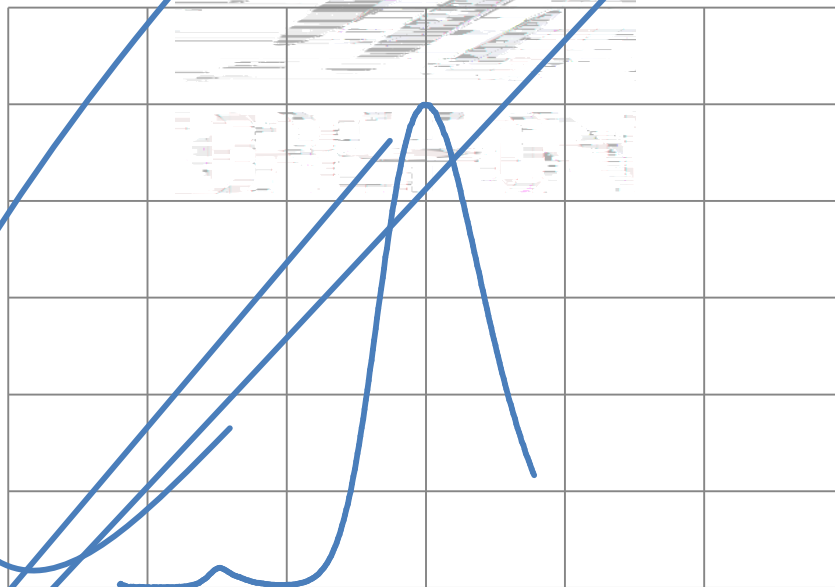


Fig. 1-14 Spectrum Distribution

2. Packaging

2.1 Packaging Specification

Package:5000pcs/reel. 5000pcs

2.1.1 Carrier Tape Dimension

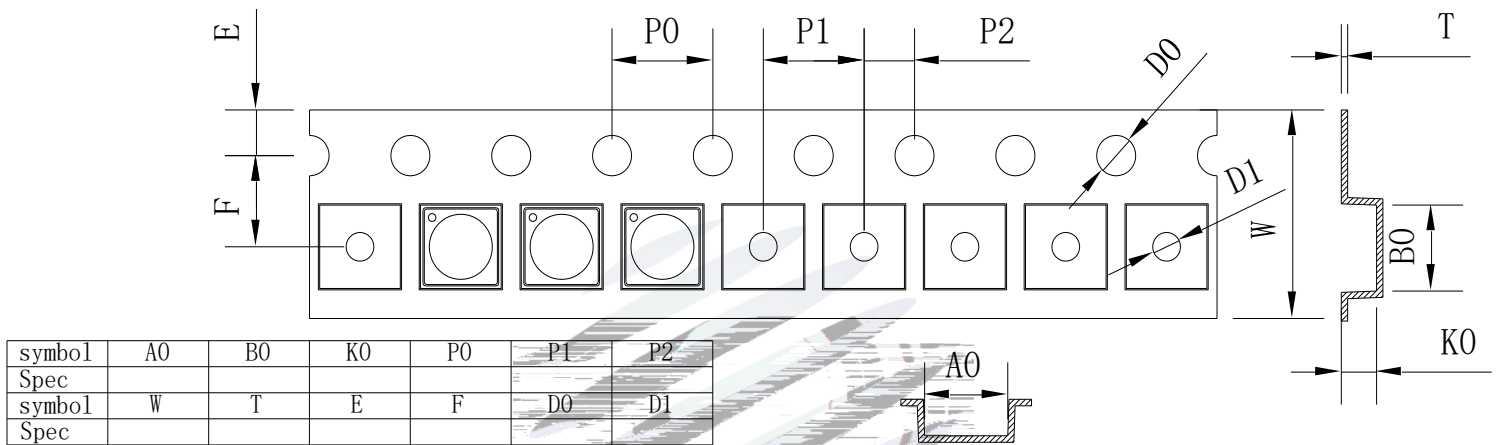


Fig.2-1 Carrier Tape Dimension

2.1.2 Reel Dimension

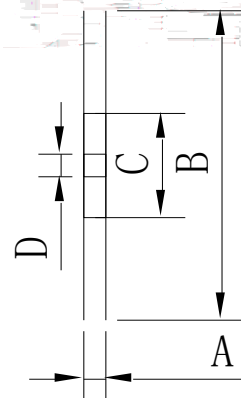
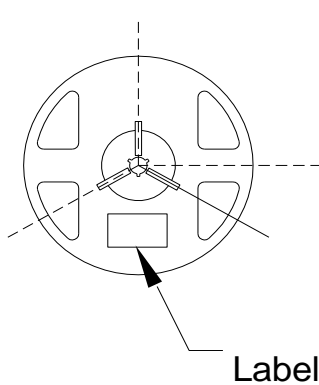


Table 2-1 Reel Dimension

A	12 0.1mm
B	180 1mm
C	60 1mm
D	13.0 0.5mm

Fig.2-2 Reel Dimension

Notes

The tolerances unless mentioned $\pm 0.1\text{mm}$. Unit : mm



2.1.3 Label Form Specification

Table 2-2 Specification

PART NO.	Part Number
SPEC NO.	Spec Number
LOT NO.	Lot Number
BIN CODE	Bin Code
Φ	Luminous flux
XY	Chromaticity Bin
V_F	Forward Voltage
WLD	Wavelength
QTY	Packing Quantity
DATE	Made Date

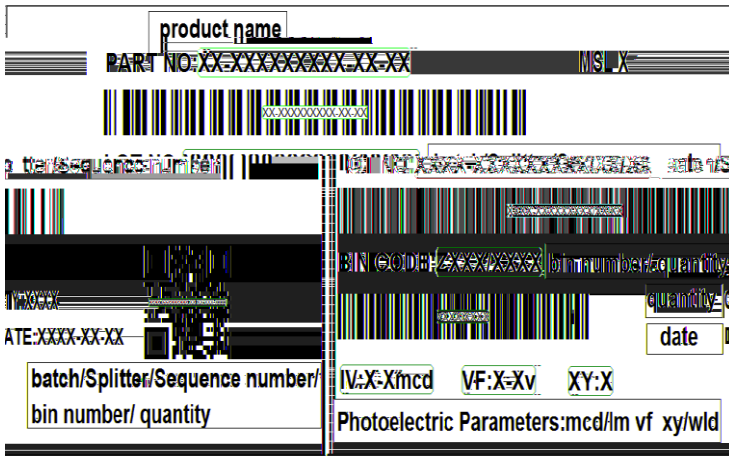


Fig. 2-3 Label Form Specification

2.2 Moisture Resistant Packing

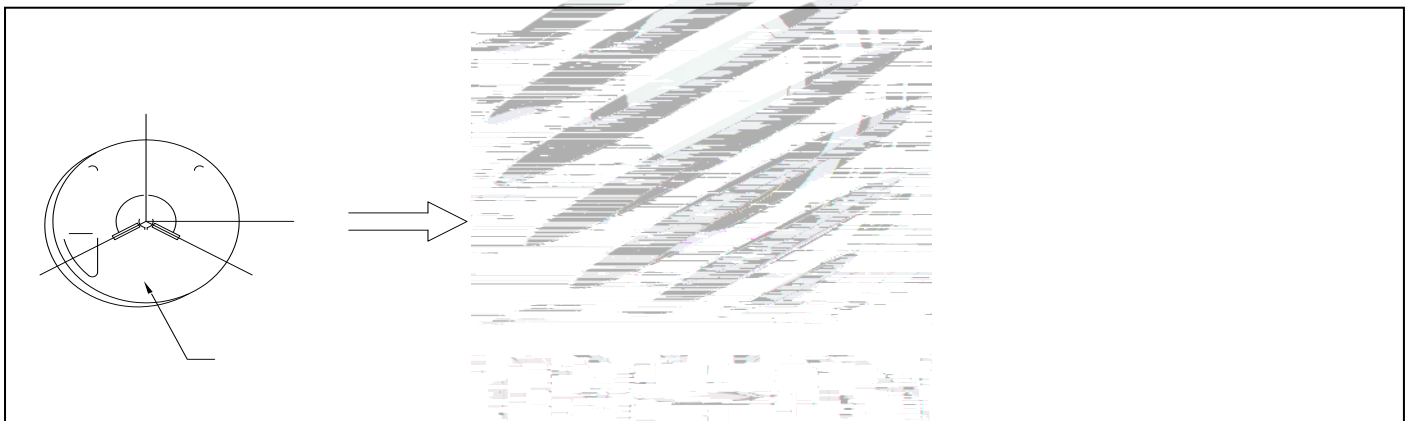


Fig.2-4Moisture Resistant Packing

2.3 Cardboard Box

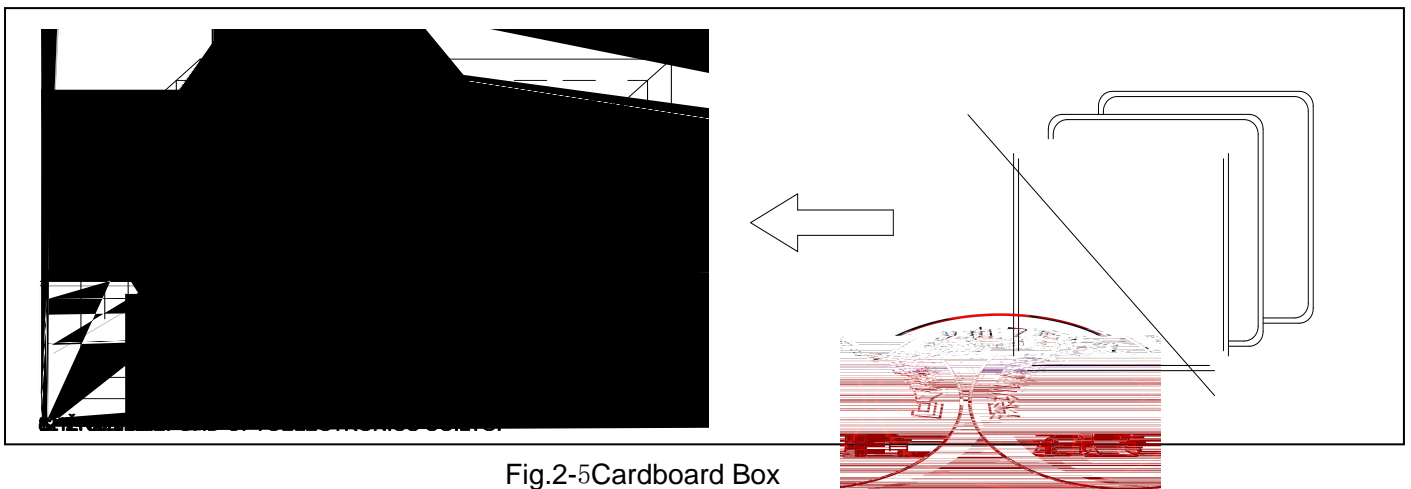


Fig.2-5Cardboard Box

2.4 Reliability Test Items And Conditions

Table 2-3 Reliability Test Items And Conditions

Test Items	Ref. Standard	Test Condition	Time	Quantity	Ac/Re /
Reflow	JESD22-B106	Temp:260 max T=10 sec	2times	20pcs.	0/1
Thermal Shock	JEITAED-4701 300307	-40 15min ↑↓10s 125 15min	300 cycle	20pcs.	0/1
High Temperature Storage	JEITAED-4701 200 201	Temp:125	1000hrs.	20pcs.	0/1
Low Temperature Storage	JEITA ED-4701 200 202	Temp:-40	1000hrs.	20pcs.	0/1
Life Test	JESD22-A108	T _A =25 I _F =150mA	1000hrs.	20pcs.	0/1
High Temperature High Humidity Life Test	JESD22-A101	85 / 85%RH I _F =150mA	100hrs.	20pcs.	0/1
Temperature Humidity Storage	JEITA ED-4701 100 103	T _A =85 RH=85%	1000hrs.	20pcs.	0/1



2.5 **Light Damage**

Table 2-4 Criteria For

	Symbol		Criteria For Judgement	
			Min.	Max.
	V_F		-	U.S.L*)x1.1
Reverse Current	I_R	$V_R = 5V$	-	U.S.L*)x2.0

Luminous Flux

 Φ $I_F = 150mA$

L.S.L*)x0.7

-

3. SMT Reflow Soldering Instructions SMT

3.1 SMT Reflow Soldering Instructions SMT

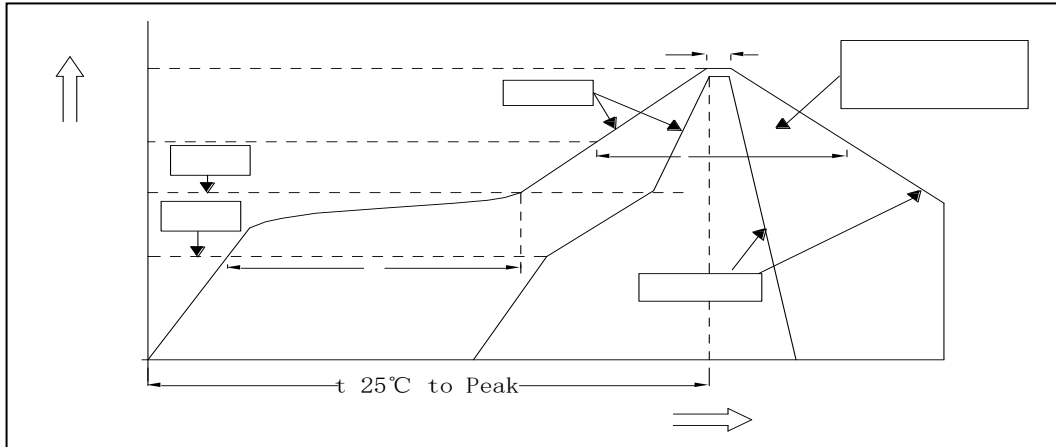


Fig.3-1 SMT Reflow Soldering Instructions SMT

Table 3-1 Reflow parameters

Average temperature rise speed	$T_{\text{max}} - T_{\text{P}}$	3 °C/ s	Max 3 °C/ s
Preheating: minimum temperature	(T_{min})	150 °C	
Preheating: Max temperature	(T_{max})	200 °C	
Preheating: Time	$T_{\text{min}} - T_{\text{max}}$	60 - 120	60s-120s
Time limited to maintain high temperature: the temperature	(T_{L})	217 °C	
Time limited to maintain high temperature: The Time	(t_{L})	60	Max 60s
Peak /Classification of temperature:	(T_{P})	260 °C	
Time limit classification of peak temperature time	t_{p}	10	Max 10s
($T_{\text{P}} - 5$ °C) Hold time within	5 °C with the actual peak temperature (T_{P})	30	Max 30s
Cooling speed		6 °C/ s	Max 6 °C/ s
25 °C	Needed time from 25 °C to T_{P}	8	Max 8 minutes

Notes

(1)Reflow soldering should not be done more than twice. If more than 24 hours between the two solderings ,LED will be damaged. 24 LED

(2)When soldering , do not put stress on the LEDs during heating.

3.1.1 Soldering Iron

(1) When do soldering by hand, keep the temperature of iron below less 300 less than 3 seconds. 300 3

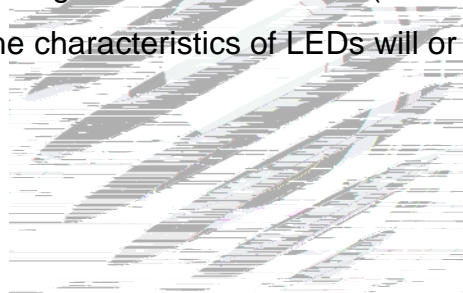
(2) Soldering by hand should be done only one time.

3.1.2 Repairing

Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable,a double-head soldering iron should be used (as below figure). It should be confirmed in advance whether the characteristics of LEDs will or not be damaged by repairing.

LED

LED



3.1.3 Cautions

(1) The encapsulated material of the LEDs is silicone. Therefore the LEDs have a soft surface on the top of package. The pressure to the top surface will be impacted on the reliability of the LEDs. Precautions should be taken to avoid the strong pressure on the encapsulated part. So when use the picking up nozz-1(re-8(73 Tm[Cau)-5(tio)-3(n)-3(s)]TJET EMC /P AMCID 60-BDC BT/F5 12.o)-13(6E

4. Handling Precautions

4.1 Handling Precautions

(1) LED operating environment and sulfur element composition cannot be over 100PPM in the LED mating usage material. This it[- 1 103.82 40.t12.96 reE Tf9433)-11(i)-7(n)-3(le)94333r5



(4) Handle the component along the side surface by using forceps or appropriate tools; Do not directly touch or Handle the silicone lens surface, it may damage the internal circuitry.

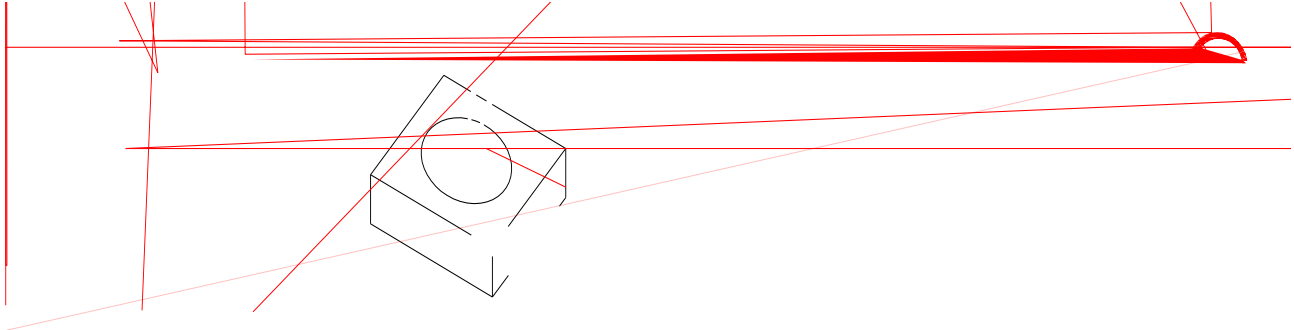
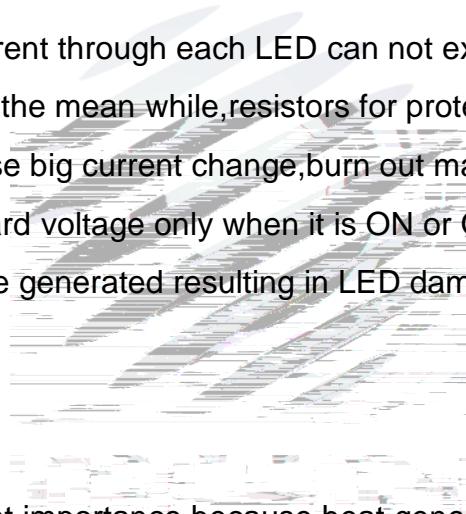


Fig 4-1Cautions

(5) In designing a circuit, the current through each LED can not exceed the absolute maximum rating specified for each LED. In the mean while, resistors for protection should be applied, otherwise slight voltage shift will cause big current change, burn out may happen. The driving circuit must be designed to allow forward voltage only when it is ON or OFF. If the reverse voltage is applied to LED, migration can be generated resulting in LED damage.



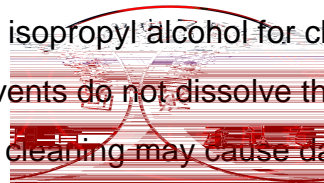
LED

LED

(6) Thermal Design is paramount importance because heat generation may result in the Characteristics decline, such as brightness decreased, Color change and so on. Please consider the heat generation of the LEDs when making the system design.

LED

(7) Compared to standard encapsulants, silicone is generally softer, and the surface is more likely to attract dust, requiring special care during processing. In cases where a minimal level of dirt and dust particles cannot be guaranteed, a suitable cleaning solution must be applied to the surface after the soldering of components. Refond suggests using isopropyl alcohol for cleaning. In case other solvents are used, it must be assured that these solvents do not dissolve the package or resin. Ultrasonic cleaning is not recommended. Ultrasonic cleaning may cause damage to the



LED.

LED

Table 4-1 Storage

Conditions		Temperature	Humidity	Time
Storage	Before Opening Aluminum Bag	30	75%	Within 1 Year From Date
	After Opening Aluminum Bag	30	60%	Recommended for use within 24 hours 24
Baking		60 5	-	24hours 24

(8) If the moisture absorbent material silica gel has faded away or the LEDs have exceeded the storage time, baking treatment should be performed after unpacking and based on the following condition 65 5 for above 24 hours.

60 5 24

If the package is flatulence or damaged, please notify the sales staff to assist.

(9) Similar to most Solid state devices; LEDs are sensitive to Electro-Static Discharge (ESD) and Electrical Over Stress (EOS).

LED

(10) Other points for attention, please refer to our relevant information.





